

SC1869 Adaptive RF Power Amplifier Linearizer

General Description

The SC1869 is part of Scintera's 2nd generation RF • PA linearizer (RFPAL[™]) family providing increased • ACLR correction over the previous generation as well . as support for EVDO, TD-SCDMA, WIMAX[®], HSDPA, LTE and TD-LTE waveforms. The SC1869 is a fullyadaptive, RFin/RFout predistortion linearization solution that precisely compensates RF power amplifier (PA) nonlinearities including AM/AM and AM/PM distortion, spectral regrowth, memory effects and other system level impairments.

The SC1869 substantially increases power amplifier • efficiency by reducing out-of-band energy. The • SC1869 is a complete system-on-chip (SoC) solution optimized for Class A/AB RF power amplifiers Benefits operating at an average power level of 500mW to . 10W (RMS). The SC1869 measures the feedback signal from the power amplifier output, and optimizes the correction function by minimizing distortion. SC1869 correction function is generated using RFdomain analog signal processing allowing the SC1869 to operate at very low power consumption.

Applications

- Cellular Infrastructure (Targeting Small Cells)
 - Single Carrier, Multi-Carrier/Standard: WCDMA/EVDO, TD-SCDMA, WIMAX, WCDMA/HSDPA, LTE & TD-LTE
 - RRU, Tower Mounted PAs, Booster Amplifiers, Microcells, Picocells, Enterprise Femtocells, DAS, AAS and MIMO Systems
- Other Applications
 - Software-Defined Radios (SDR), HMS/Mobile 0 Military Communications and White Space
 - Public Safety Mobile and Portable Transmitters
 - Customer Premises Equipment
 - Any Application Requiring Linearization of Class A/AB PAs
- Wide Range of PAs and Output Power •
 - o Amplifier: Class A/AB
 - PA output power: up to 10W (RMS)
 - PA Process: LDMOS, GaAs and InGaP

Features

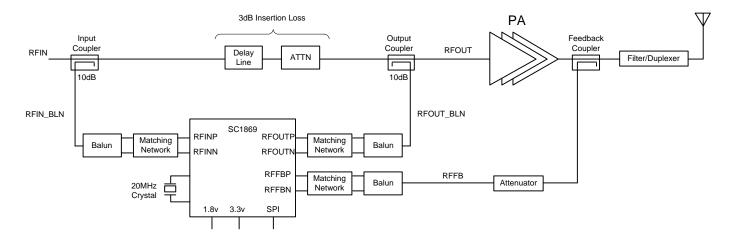
- RFin/RFout PA Linearizer SoC in Standard CMOS
- Fully Adaptive Compensation
- Low Power Consumption:
 - Duty-Cycled (9%) Feedback: 420mW 0
 - Full Adaptation: 1.06W 0
- Frequency Range: 698MHz to 2800MHz
- Input Signal Bandwidth: Up to 20MHz
- Up to 28dB ACLR and 38dB IMD Improvement*
- Packaged in 9mm x 9mm QFN Package
- Operating Case Temperature: -40°C to +100°C
- Fully RoHS Compliant, Green Materials
- Pin Compatible with SC1887 and SC1869

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- Ease of Use
 - Integrated RFin/RFout Solution 0
 - 0 **Operates Over Wide Frequency Band**
 - No Software Development Required 0
 - No Training, Algorithm Development, Control 0 Required – Automatically Calibrates and Adjusts to the Signal and PA Environment Supports Wide Range of Modulation Schemes 0
- Smaller Total System Form Factors
 - Reduced Heat Sink Size and Weight 0
 - Small Implementation Size ($< 6.5 \text{ cm}^2$) 0
- **Reduces Operating Costs**
 - **Reduces Energy Consumption Supporting** 0 **Green Initiatives**
 - Reduces Amplifier Power Consumption and **Thermal Dissipation**
 - **Increases Amplifier Reliability**
 - **Reduces BOM Costs and Total Volume**
 - Power Supply, Heat Sink and Enclosure 0
 - Reduced Back-off Reduces Transistor Costs 0

*Performance dependent on amplifier, bias, and waveform.

Application Block Diagram



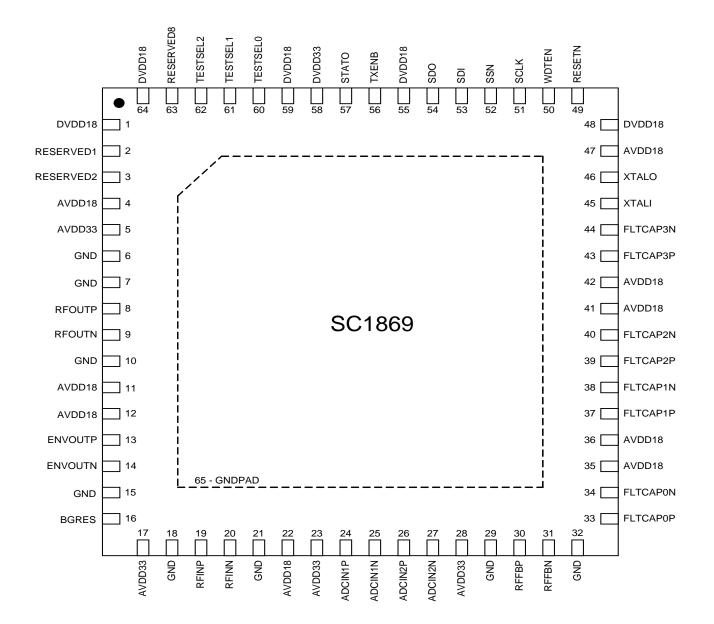
Introduction to Predistortion Using the SC1869

Wideband signals in today's telecommunications systems have high peak-to-average ratios and stringent spectral regrowth specifications. These specifications place high linearity demands on power amplifiers. Linearity may be achieved by backing off output power at the price of reducing efficiency. However, this increases the component and operating costs of the power amplifier. Better linearity may be achieved through the use of digital predistortion and other linearization techniques, but many of these are time consuming and costly to implement.

Wireless service providers are deploying networks with wider coverage, greater subscriber density, and higher data rates. These networks require more efficient power amplifiers. Additionally, the emergence of distributed architectures and active antenna systems is driving the need for smaller and more efficient power amplifier implementations. Further, there continues to be a strong push toward reducing the total capital and operating costs of base stations.

With the SC1869, the complex signal processing is done in the RF domain resulting in a simple system-onchip that offers wide signal bandwidth, broad frequency of operation, and very low power consumption. It is an elegant solution that reduces development costs and speeds time to market. Applicable across a broad range of signals—including 2G, 3G, 4G wireless, and other modulation types—the powerful analog signal processing engine is capable of linearizing the most efficient power amplifier topologies. The SC1869 is a true RFin and RFout solution, supporting modular power amplifier designs that are independent of the baseband and transceiver subsystems. The SC1869 delivers the required efficiency and performance demanded by today's wireless systems.

Pin Configuration (Top View)



Pin Description

PIN	NAME	TYPE	FUNCTION		
1	DVDD18		+1.8V DC Supply Voltage for digital circuits.		
		Supply			
2	RESERVED1	Analog Out Reserved	Do not connect. Reserved for internal use.		
3	RESERVED2	Analog Out Reserved	Do not connect. Reserved for internal use.		
4	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
5	AVDD33	Supply	+3.3V DC Supply Voltage for analog circuits.		
6	GND	Supply	Ground.		
7	GND	RF Shield	Ground for shield of RF signal.		
8	RFOUTP		RF Output Signal, differential output. See S-parameters for		
9	RFOUTN	Analog Out	complex impedance values.		
10	GND	RF Shield	Ground for shield of RF signal.		
11	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
12	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
13	ENVOUTP	Analog Out			
14	ENVOUTN	Reserved	Envelope Out. Do not connect. Reserved for future use.		
15	GND	Supply	Ground.		
16	BGRES	Analog In	Bandgap Resistor.		
17	AVDD33	Supply	+3.3V DC Supply Voltage for analog circuits.		
18	GND	RF Shield	Ground for shield of RF signal.		
19	RFINP		RF Input Signal, differential input. See S-parameters for complex		
20	RFINN	Analog In	impedance values.		
21	GND	RF Shield	Ground for shield of RF signal.		
22	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
23	AVDD33	Supply	+3.3V DC Supply Voltage for analog circuits.		
24	ADCIN1P	Analog In	Do not connect. Reserved for future use. Low frequency ADC#1 positive analog input (requires separate FW activation).		
25	ADCIN1N	Reserved	Do not connect. Reserved for future use. Low frequency ADC#1 negative analog input (requires separate FW activation).		
26	ADCIN2P	Analog In	Do not connect. Reserved for future use. Low frequency ADC#2 positive analog input (requires separate FW activation).		
27	ADCIN2N	Reserved	Do not connect. Reserved for future use. Low frequency ADC#2 negative analog input (requires separate FW activation).		
28	AVDD33	Supply	+3.3V DC Supply Voltage for analog circuits.		
29	GND	RF Shield	Ground for shield of RF signal.		
30	RFFBP	Analog In	RF Feedback Signal, differential input. See S-parameters for		
31	RFFBN		complex impedance values.		
32	GND	RF Shield	Ground for shield of RF signal.		

Pin Description (continued)

PIN	NAME	TYPE	FUNCTION		
33	FLTCAP0P				
34	FLTCAPON	Analog Out	Dedicated external filter capacitor #0.		
35	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
36	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
37	FLTCAP1P		Dedicated external filter consciter #1		
38	FLTCAP1N	Analog Out	Dedicated external filter capacitor #1.		
39	FLTCAP2P	Apolog Out	Dedicated external filter conseitor #2		
40	FLTCAP2N	Analog Out	Dedicated external filter capacitor #2.		
41	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
42	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
43	FLTCAP3P	Analog Out	Dedicated external filter capacitor #2		
44	FLTCAP3N	Analog Out	Dedicated external filter capacitor #3.		
45	XTALI	Analog In	20 MHz clock reference from crystal or resonator.		
46	XTALO	Analog Out			
47	AVDD18	Supply	+1.8V DC Supply Voltage for analog circuits.		
48	DVDD18	Supply	+1.8V DC Supply Voltage for digital circuits.		
49	RESETN	Digital In	Reset when "Low". Has internal pull-up to DVDD33.		
50	WDTEN	Digital In Reserved	Watch Dog Timer Enable. WDTEN enabled when high. Has internal pull-up to DVDD33. See applications schematic for further details.		
51	SCLK	Digital In	SPI clock. Has internal pulldown to GND.		
52	SSN	Digital In	SPI slave select enabled "Low". Has internal pull-up to DVDD33.		
53	SDI	Digital In	SPI slave data input to RFPAL. Has internal pulldown to GND.		
54	SDO	Digital Out	SPI slave data output from RFPAL. Three-state. DVDD33 logic.		
55	DVDD18	Supply	+1.8V DC Supply Voltage for digital circuits.		
56	TXENB	Digital In Reserved	Transmit Enable. Do not connect. Reserved for future use. Has internal pullup to DVDD33. See applications schematic for further details.		
57	STATO	Digital Out	General purpose Status Output as defined in Firmware Release Notes. Open-drain output with internal pullup to DVDD33.		
58	DVDD33	Supply	+3.3V DC Supply Voltage for digital circuits.		
59	DVDD18	Supply	+1.8V DC Supply Voltage for digital circuits.		
60	TESTSEL0	Digital In	Test Select 0. Required for FW upgrades. Has internal pulldown to GND. See applications schematic for further details.		
61	TESTSEL1	Digital In Reserved	Do not connect. Reserved for internal use. Has internal pulldown to GND.		
62	TESTSEL2	Digital In Reserved	Do not connect. Reserved for internal use. Has internal pulldown to GND.		
63	RESERVED8	Digital In Reserved	Do not connect. Reserved for internal use. Has internal pulldown to GND.		
64	DVDD18	Supply	+1.8V DC Supply Voltage for digital circuits.		
65	GNDPAD	Supply	Common Ground for entire integrated circuit. Also provides path for thermal dissipation.		

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (VDD33 to GND)0.3V to +3.8V
Supply Voltage (VDD18 to GND)0.2V to +2.2V
Input Voltage (1.8V pins)0.2V to (VDD18 + 0.2V)
Input Voltage (3.3V pins)0.3V to (VDD33 + 0.3V)
Input into the Balun (RMS)+7dBm
Junction Temperature+150°C
Storage Temperature65°C to +150°C

OPERATING RATING

Operating Case Temperature.....-40°C to +100°C

Warning: Any stress beyond the ranges indicated may damage the device permanently. The specified stress ratings do not imply functional performance in these ranges. Exposure of the device to the absolute maximum ratings for extended periods of time is likely to degrade the reliability of this product.

DC CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNITS
Supply Voltage (VDD33 to GND)	3.1	3.3	3.5	V
Supply Voltage (VDD18 to GND)	1.7	1.8	1.9	V
Supply Peak Current (VDD33 to GND) ^{1,2,3,5}		59		mA
Supply Peak Current (VDD18 to GND) ^{1,2,3,5}		592		mA
Average Power Dissipation: Full-Scale Adaptation, Track		1060		mW
Average Power Dissipation: Duty-Cycled Feedback ^{2,4,5}		350		mW

Note 1: Peak current includes supply decoupling network. Refer to Hardware Design Guide for proper sizing of the on-board regulators. **Note 2:** Characterized at typical voltages, +25°C operating case temperature and 20MHz input signal BW.

Note 3: Continuous adaptation and tracking (100% duty-cycled feedback).

Note 4: Duty-cycled feedback power dissipations averaged over ON time of 100ms (9%) and OFF time of 1.024s (91%).

Note 5: Power dissipation may be FW dependent. Refer to the FW release notes for any changes to values listed above.

PARAMETER	SYMBOL	CONDITIONS	MIN	RECOMMENDED	MAX	UNITS
Operating Frequency ¹	f		698		2800	MHz
RFIN_BLN Range for Maximum Correction	$P_{RFIN_BLN_P}$	Peak power	-4	4	6	dBm
RFIN_BLN Range for Maximum Correction	P_{RFIN_BLN}	RMS power ²	-9	-6	-4	dBm
RFFB_BLN Range for Maximum Correction	P_{RFFB}_{BLN}	Peak power	-14	-4	-2	dBm
RFFB_BLN Range for Maximum Correction	P_{RFFB_BLN}	RMS power ²	-19	-14	-12	dBm
RFIN_BLN Operating Range	P_{RFIN_BLN}	RMS power ²	-40		-4	dBm
RFFB_BLN Operating Range	P_{RFFB_BLN}	RMS power ²	-45		-12	dBm
RF Input Signal Peak-to Avg. Ratio ³		$CCDF^4$ probability = 10^{-4}		5 to 10		dB
Input Signal Bandwidth	BW _{signal}		1.2		20	MHz
Noise Power ⁵		Referred to 0dBm at PA input		-140	-137	dBm/Hz

RADIO FREQUENCY SIGNALS

Note 1: See Operating Frequency Ranges table for frequency limits of each defined band.

Note 2: A peak to average ratio (PAR) of 5dB to 10dB is used for this table.

Note 3: Higher PAR values can be supported but at a reduction to a combination of the input signal range and IM correction limits.

Note 4: CCDF = complementary cumulative distribution function; a measurement of peak to average ratio or crest factor.

Note 5: Worst case over PVT.

OPERATING FREQUENCY RANGES

FREQUENCY RANGE ¹	RECOMMENDED APPLICATIONS	DESIGNATION
698MHz to 960MHz	Lowband cellular (698MHz to 960MHz)	-04
800MHz to 1600MHz	IF for SATCOMM (1000MHz to 1400MHz)	-05
1350MHz to 2700MHz	LTE for Japan (1400MHz to 1510MHz)	-06
1600MHz to 2800MHz	Highband cellular (1600MHz to 2800MHz)	-07

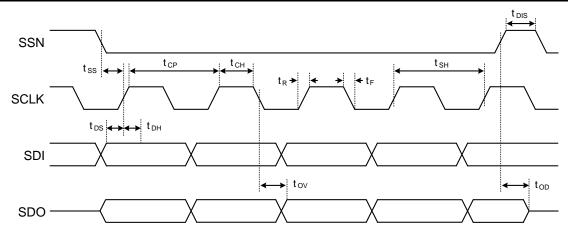
Note 1: Default is -07. May be reprogrammed by user for other ranges listed above. Refer to Design Guide for programming information.

DIGITAL I/O-DC CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CMOS Input Logic-Low	VIL		-0.3		0.8	V
CMOS Input Logic-High	V _{IH}	VDD = 3.3V	2.0			V
CMOS Output Logic-Low	V _{OL}				0.4	V
CMOS Output Logic-High	V _{OH}	VDD = 3.3V	2.4			V
SDO CMOS Output Current	I _{OL} /I _{OH}	Three-State	-4.0		+4.0	mA
STATO CMOS Output Current	I _{OL} /I _{OH}	Open Drain	-4.0		0.0	mA

SERIAL PERIPHERAL INTERFACE (SPI) BUS SPECIFICATIONS

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Select Setup Time	t _{SS}		100			ns
Select Hold Time	t _{SH}		250			ns
Select Disable Time	t _{DIS}		100			ns
Data Setup Time	t _{DS}		25			ns
Data Hold Time	t _{DH}		45			ns
Rise Time	t _R				25	ns
Fall Time	t _F				25	ns
Clock Period	t _{CP}		250			ns
Clock High Time	t _{CH}		100			ns
Time to Output Valid	t _{ov}				100	ns
Output Data Disable	t _{OD}				0	ns



Use of the SPI is optional as SC1889 is capable of fully autonomous operation. Use of the SPI interface offers the user access to certain monitoring and diagnostic functions, as well as other planned advanced features. The SPI bus interface is also used to program the internal EEPROM, allowing changes to the operating frequency range, field upgrades, and firmware updates.

CRYSTAL REQUIREMENTS

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ESR					50	Ω
Capacitive Load to Ground				10	12	pF
Frequency Accuracy					250	ppm
Frequency Drift		Including aging and temperature			100	ppm

Top Mark



LINE	TOP MARK	DESCRIPTION
1	SCINTERA	Company Name
2	SC1869	Product Part Number
2	А	Product Revision
2		Product Configuration (PC): BLANK = RFPAL Base Configuration
3	XXXXXXXXXXX	Foundry Lot Number (up to 10 characters)
4	WW	Date Code - Work Week
4	ΥY	Date Code - Year
4	RRRR	Reserved

ESD



ESD (Electrostatic discharge) sensitive device. Although this product incorporates ESD protection circuitry, permanent damage may occur on devices subjected to electrostatic discharges. Proper ESD precautions are recommended to avoid performance degradation or device failure.

ELECTROSTATIC DISCHARGE (ESD) PROTECTION CHARACTERISTICS

TEST METHODOLOGY	CLASS	VOLTAGE	UNIT
Human Body Model (per JESD22-A114)	1C	1000	V
Charge Device Model (per JESD22-C101)	11	250	V

Ordering Information

PART	DESCRIPTION
SC1869A-00B00	IC, RFPAL, 698MHz to 2800MHz, FW3.0.21.01

Shipping designator: E = 7" tape and reel. Append shipping designator (E) at end of part number. If left blank, designates bulk shipping option.

Revision History

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
0.1	7/14	Initial release	—

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